

# RowPress

## Amplifying Read Disturbance in Modern DRAM Chips

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**Published at ISCA'23, Distinguished Artifact Award  
IEEE MICRO Top Picks 2023**

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# High-Level Summary

- We demonstrate and analyze **RowPress, a new read disturbance phenomenon** that causes bitflips in real DRAM chips
- We show that RowPress is **different from the RowHammer vulnerability**
- We demonstrate RowPress **using a user-level program** on a real Intel system with real DRAM chips
- We provide **effective solutions** to RowPress

# Outline

**DRAM Background**

What is RowPress?

Real DRAM Chip Characterization

Characterization Methodology

Key Characteristics of RowPress

Real-System Demonstration

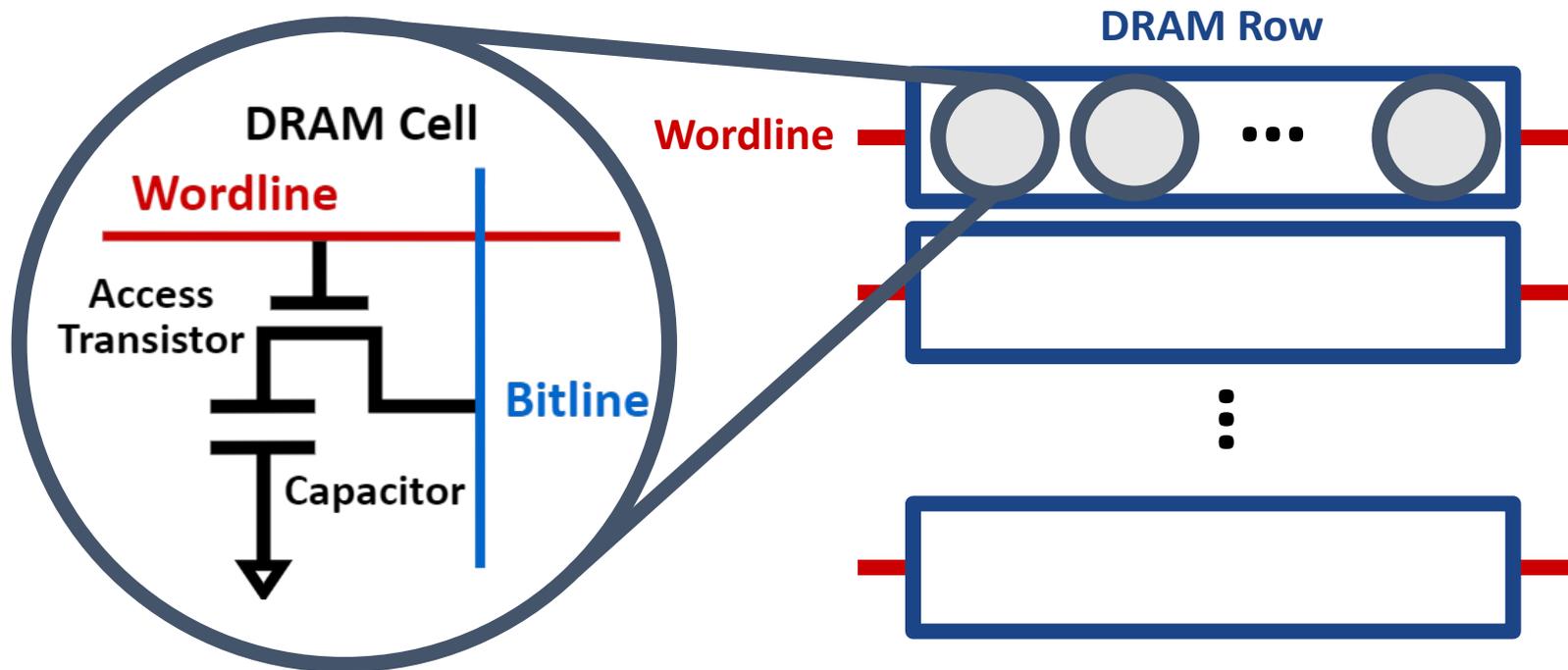
Mitigating RowPress

Conclusion

# DRAM Organization

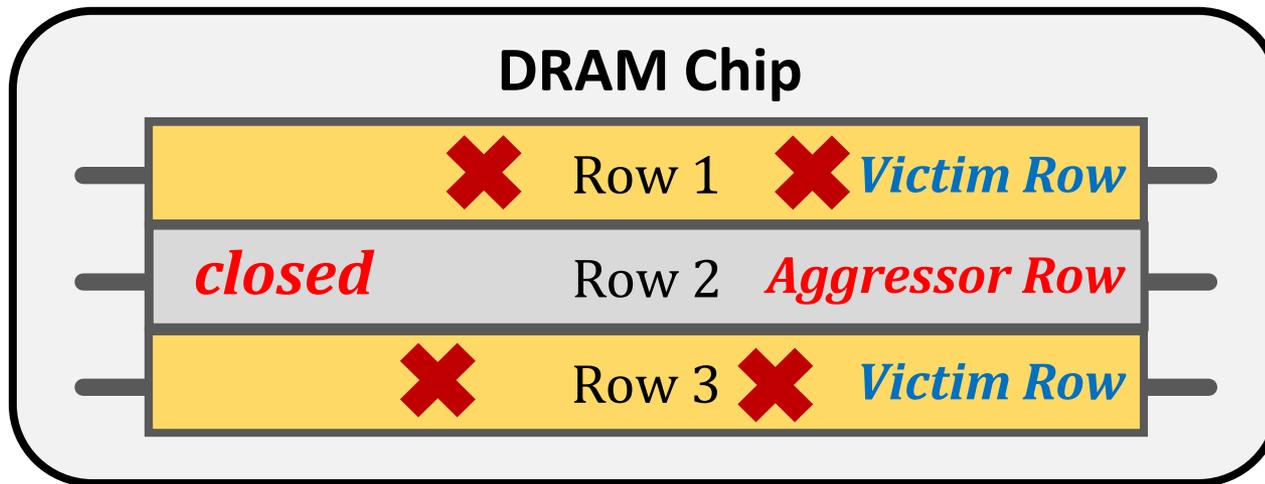
DRAM is the prevalent technology for main memory

- A **DRAM cell** stores 1 bit of information in a **leaky** capacitor
- DRAM cells are organized into **DRAM rows**



# Read Disturbance in DRAM

- Read disturbance in DRAM breaks memory isolation
- **Prominent example: RowHammer**



Repeatedly **opening (activating)** and **closing** a DRAM row **many times** causes **RowHammer bitflips** in adjacent rows

# Are There Other Read-Disturb Issues in DRAM?

- RowHammer is the only studied read-disturb phenomenon
- Mitigations work by detecting **high row activation count**

What if there is another read-disturb phenomenon that **does NOT rely on high row activation count**?



[https://www.reddit.com/r/CrappyDesign/comments/arw0q8/now\\_this\\_this\\_is\\_poor\\_fencing/](https://www.reddit.com/r/CrappyDesign/comments/arw0q8/now_this_this_is_poor_fencing/)

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# What is RowPress?

Keeping a DRAM row **open for a long time** causes bitflips in adjacent rows

These bitflips do **NOT** require many row activations

**Only one activation** is enough in some cases!



Now, let's see how this is **different from RowHammer**

# RowPress vs. RowHammer

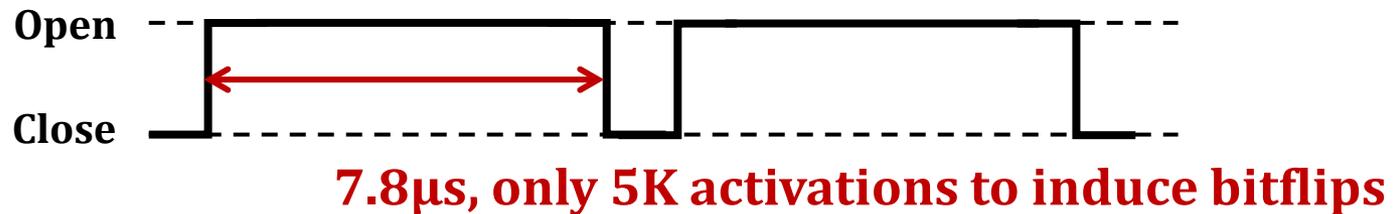
Instead of using a high activation count,

☞ increase the time that the aggressor row stays open

**RowHammer**  
**Aggressor Row**



**RowPress**  
**Aggressor Row**



We observe bitflips even with **ONLY ONE activation** in extreme cases where the row stays open for 30ms

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# Major Takeaways from Real DRAM Chips

RowPress significantly **amplifies** DRAM's vulnerability to **read disturbance**

RowPress has a **different** underlying failure **mechanism** from RowHammer

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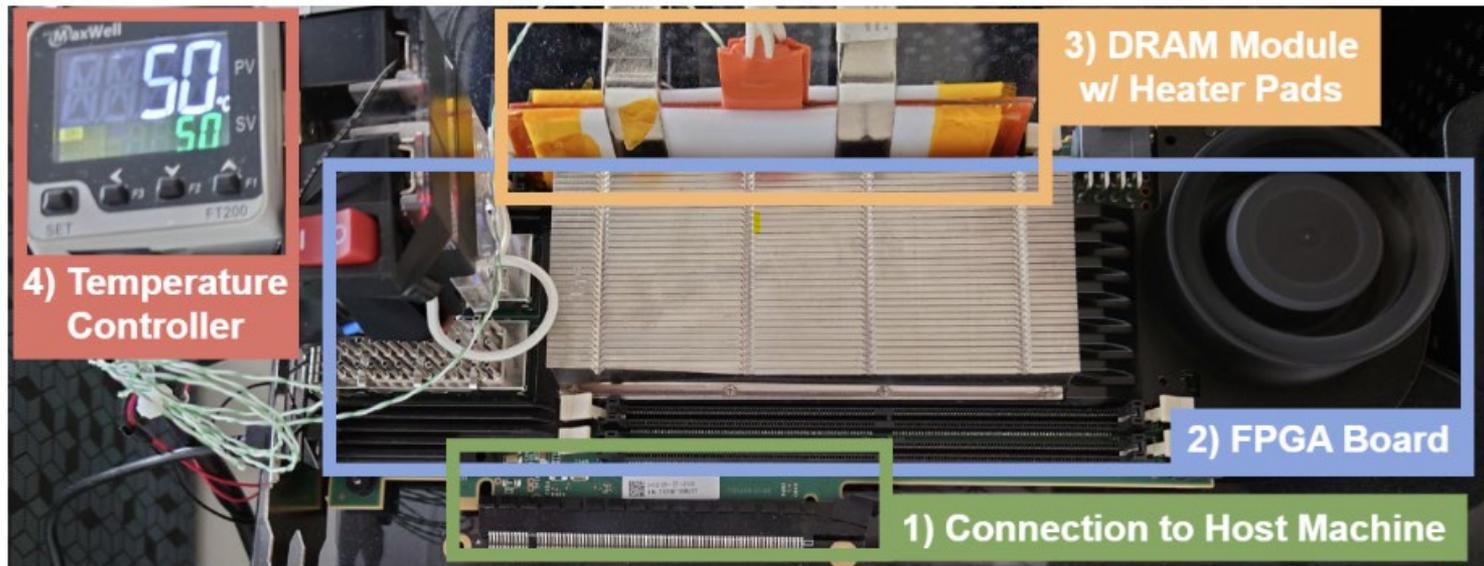
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# Characterization Methodology (I)

## FPGA-based DDR4 testing infrastructure

- Developed from [SoftMC \[Hassan+, HPCA'17\]](#) and [DRAM Bender \[Olgun+, TCAD'23\]](#)
- **Fine-grained control** over DRAM commands, timings, and temperature



# Characterization Methodology (II)

## DRAM chips tested

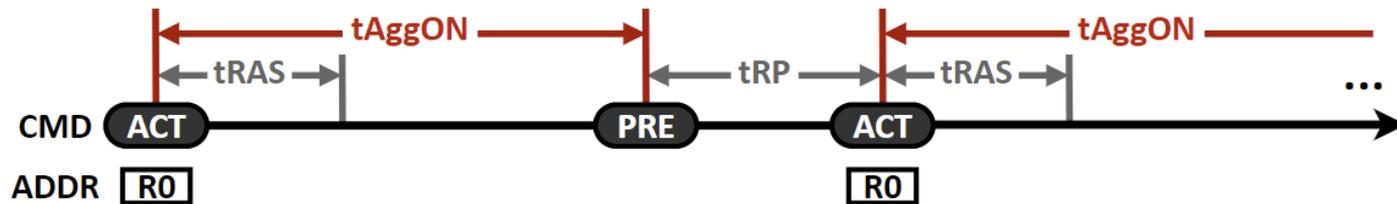
- 164 DDR4 chips from all 3 major DRAM manufacturers
- Covers different die densities and revisions

| Mfr.                 | #DIMMs | #Chips | Density | Die Rev. | Org. | Date  |
|----------------------|--------|--------|---------|----------|------|-------|
| Mfr. S<br>(Samsung)  | 2      | 8      | 8Gb     | B        | x8   | 20-53 |
|                      | 1      | 8      | 8Gb     | C        | x8   | N/A   |
|                      | 3      | 8      | 8Gb     | D        | x8   | 21-10 |
|                      | 2      | 8      | 4Gb     | F        | x8   | N/A   |
| Mfr. H<br>(SK Hynix) | 1      | 8      | 4Gb     | A        | x8   | 19-46 |
|                      | 1      | 8      | 4Gb     | X        | x8   | N/A   |
|                      | 2      | 8      | 16Gb    | A        | x8   | 20-51 |
|                      | 2      | 8      | 16Gb    | C        | x8   | 21-36 |
| Mfr. M<br>(Micron)   | 1      | 16     | 8Gb     | B        | x4   | N/A   |
|                      | 2      | 4      | 16Gb    | B        | x16  | 21-26 |
|                      | 1      | 16     | 16Gb    | E        | x4   | 20-14 |
|                      | 2      | 4      | 16Gb    | E        | x16  | 20-46 |
|                      | 1      | 4      | 16Gb    | F        | x16  | 21-50 |

# Characterization Methodology (III)

**Metric:** The minimum number of aggressor row activations in total to cause at least one bitflip (**ACmin**)

**Access Pattern:** Single-sided (i.e., only one aggressor row). Sweep aggressor row on time (**tAggON**) from 36ns to 30ms



**Data Pattern:** Checkerboard (0xAA in aggressor and 0x55 in victim)

**Temperature:** 50°C

**Algorithm:** Bisection-based ACmin search

- Each search iteration is capped at 60ms (<64ms refresh window)
- Repeat 5 times and report the minimum ACmin value observed
- Sample 3072 DRAM rows per chip

[More sensitivity studies in the paper]

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# Major Takeaways from Real DRAM Chips

RowPress significantly **amplifies** DRAM's vulnerability to **read disturbance**

RowPress has a **different** underlying failure **mechanism** from RowHammer

# Key Characteristics of RowPress

## Amplifying read disturbance in DRAM

- Reduces the minimum number of row activations needed to induce a bitflip ( $AC_{min}$ ) by **1-2 orders of magnitude**
- In extreme cases, activating a row **only once** induces bitflips
- Gets worse as **temperature increases**

## Different from RowHammer

- Affects a **different set of cells** compared to RowHammer and retention failures
- **Behaves differently** as access pattern or temperature changes compared to RowHammer

# Key Characteristics of RowPress

## Amplifying read disturbance in DRAM

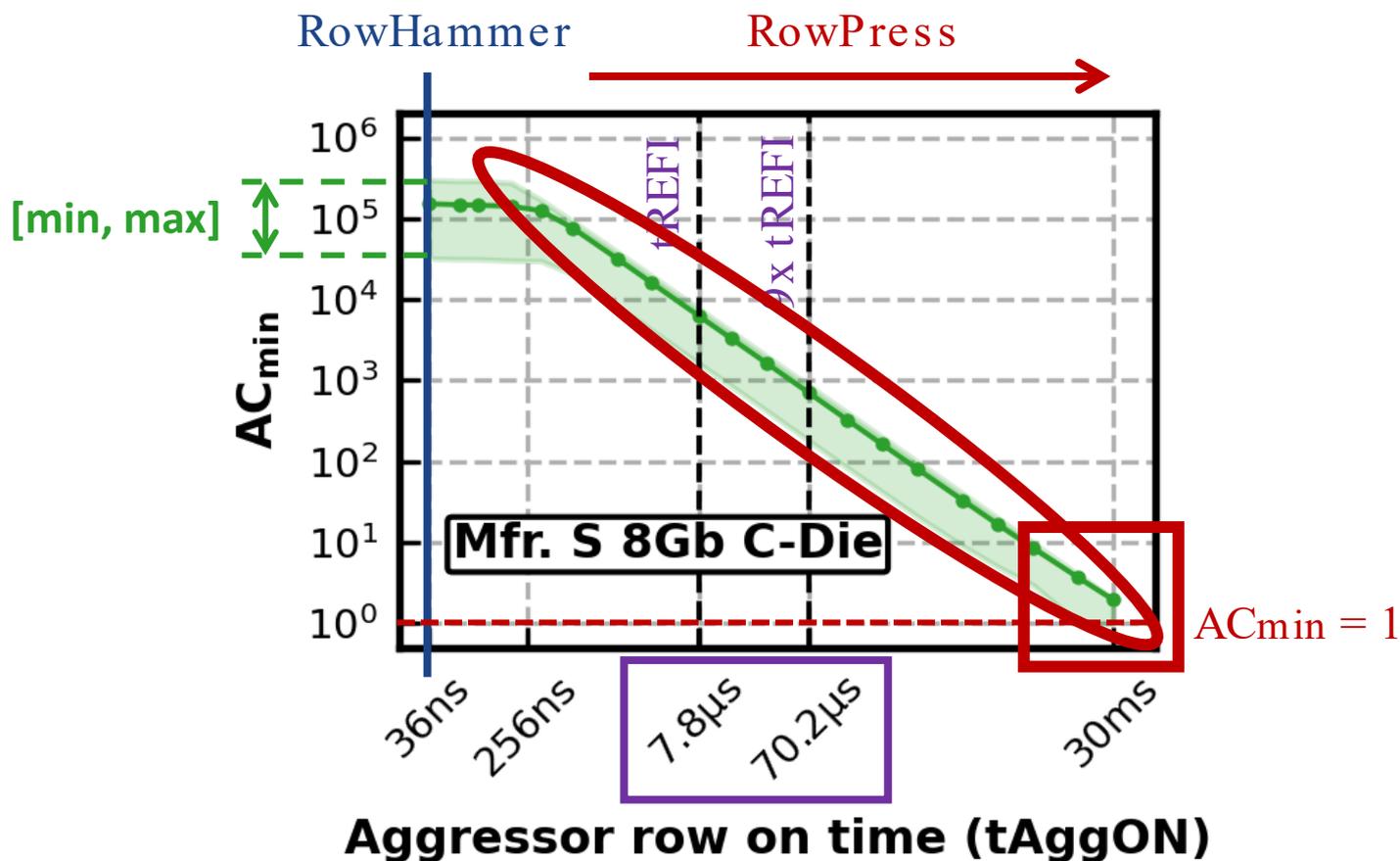
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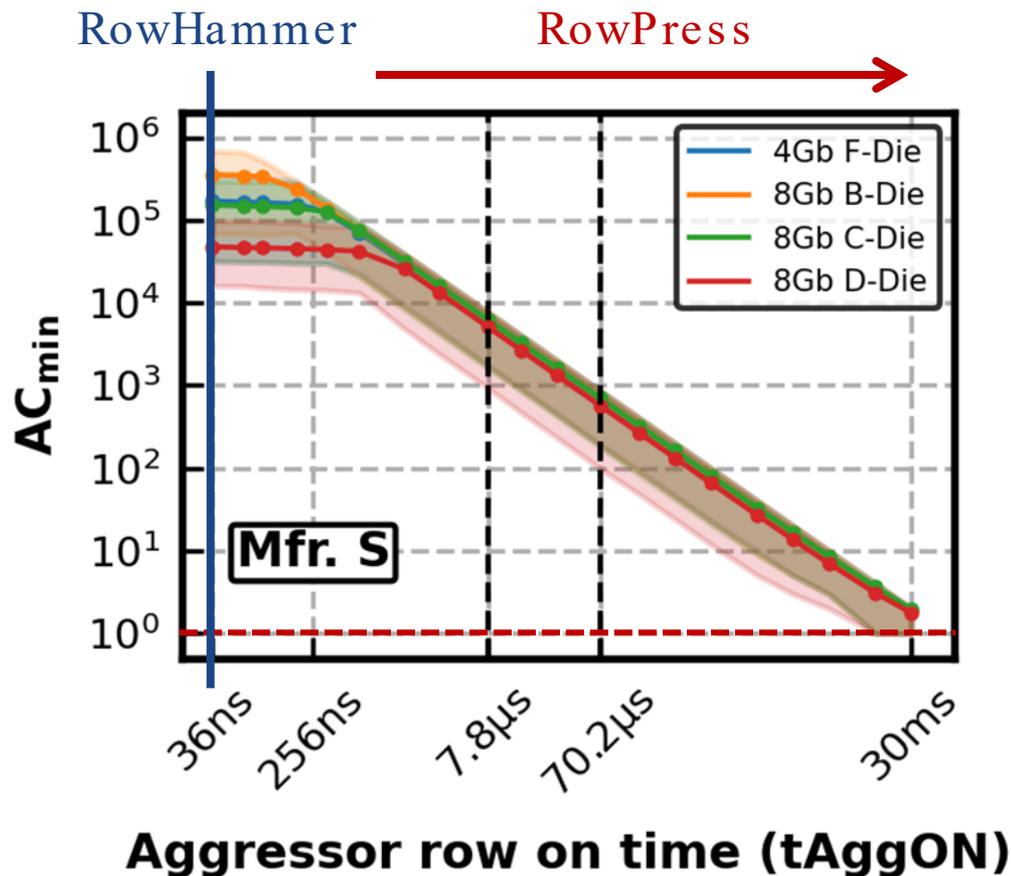
# Amplifying Read Disturbance (I)

How **minimum activation count to induce a bitflip ( $AC_{min}$ )** changes as **aggressor row on time ( $t_{AggON}$ )** increases



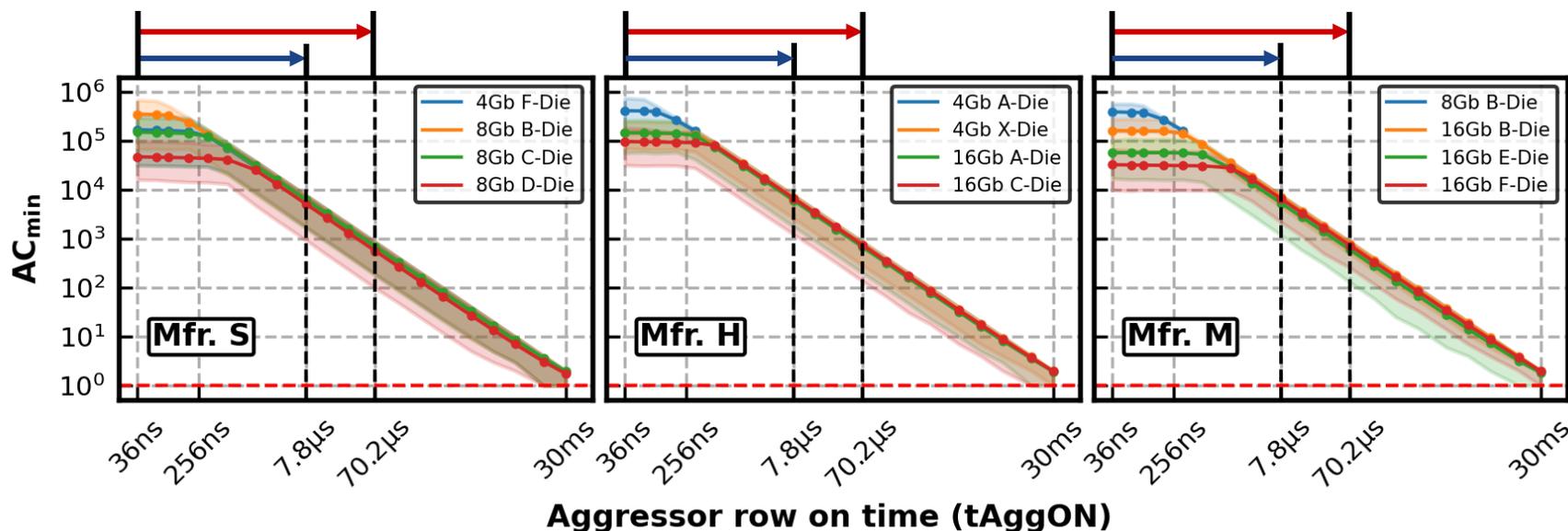
# Amplifying Read Disturbance (II)

How **minimum activation count to induce a bitflip ( $AC_{min}$ )** changes as **aggressor row on time ( $t_{AggON}$ )** increases



# Amplifying Read Disturbance (III)

How **minimum activation count to induce a bitflip ( $AC_{min}$ )** changes as **aggressor row on time ( $t_{AggON}$ )** increases



$AC_{min}$  reduces by **21X** on average when  $t_{AggON}$  increases from 36ns to **7.8 $\mu$ s**

**191X**

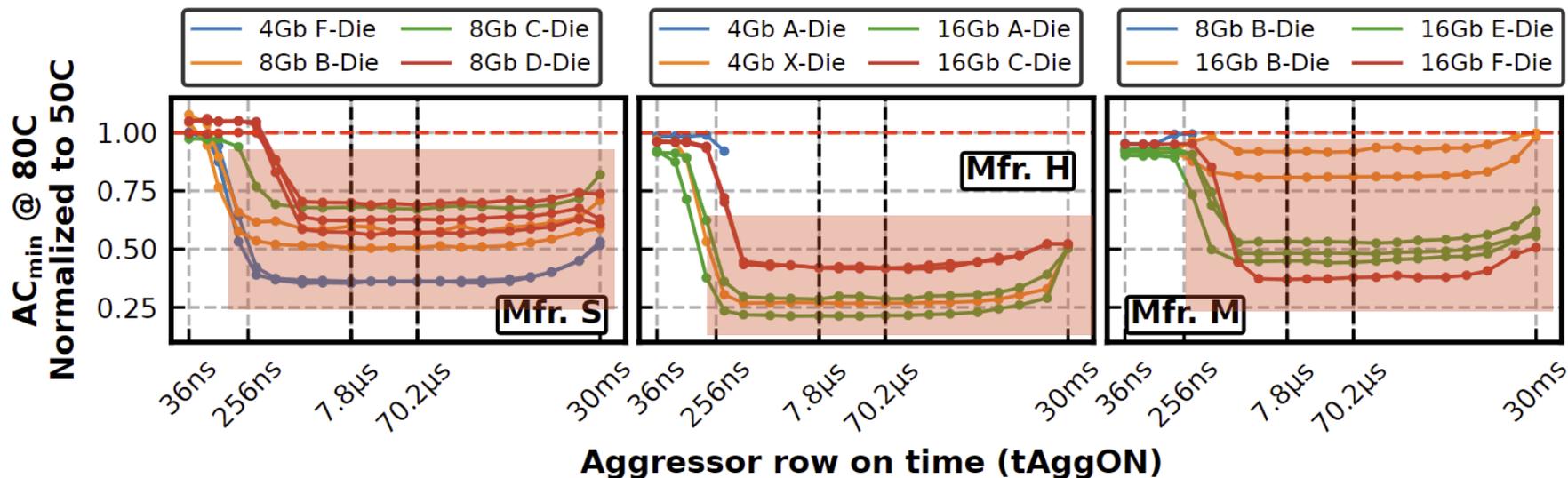
**70.2 $\mu$ s**

**RowPress significantly reduces  $AC_{min}$  as  $t_{AggON}$  increases**

# Amplifying Read Disturbance (IV)

## AC<sub>min</sub> @ 80°C normalized to AC<sub>min</sub> @ 50°C

- Data point below 1 means fewer activations to cause bitflips @ 80°C compared to 50°C



When  $t_{AggON}$  is 7.8 μs, RowPress **requires about 50% fewer activations to induce bitflips at 80°C compared to 50°C**

**RowPress gets worse as temperature increases**

# Key Characteristics of RowPress

## Amplifying read disturbance in DRAM

- Reduces the minimum number of row activations needed to induce a bitflip ( $AC_{min}$ ) by **1-2 orders of magnitude**
- In extreme cases, activating a row **only once** induces bitflips
- Gets worse as **temperature increases**

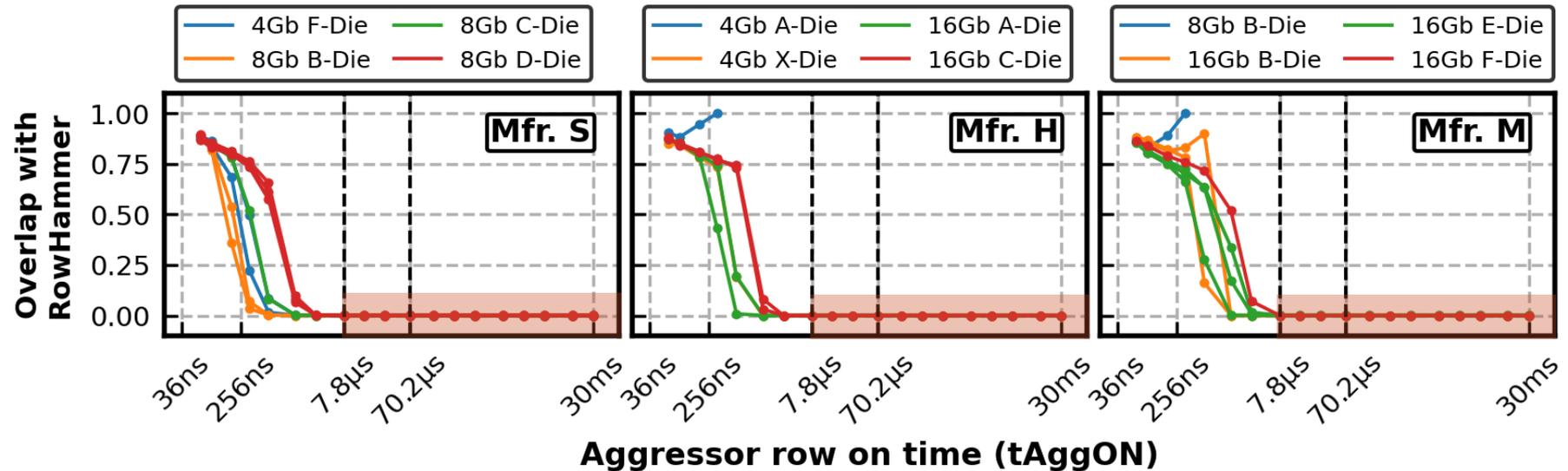
## Different from RowHammer

- Affects a **different set of cells** compared to RowHammer and retention failures
- **Behaves differently** as access pattern or temperature changes compared to RowHammer

# Difference Between RowPress and RowHammer (I)

## Cells vulnerable to RowPress vs. RowHammer

- Cells vulnerable to RowPress (RowHammer) are those that flip @ ACmin
- $$\text{Overlap} = \frac{\text{Number of Cells Vulnerable to Both RowPress and RowHammer}}{\text{Number of Cells Vulnerable to RowPress}}$$

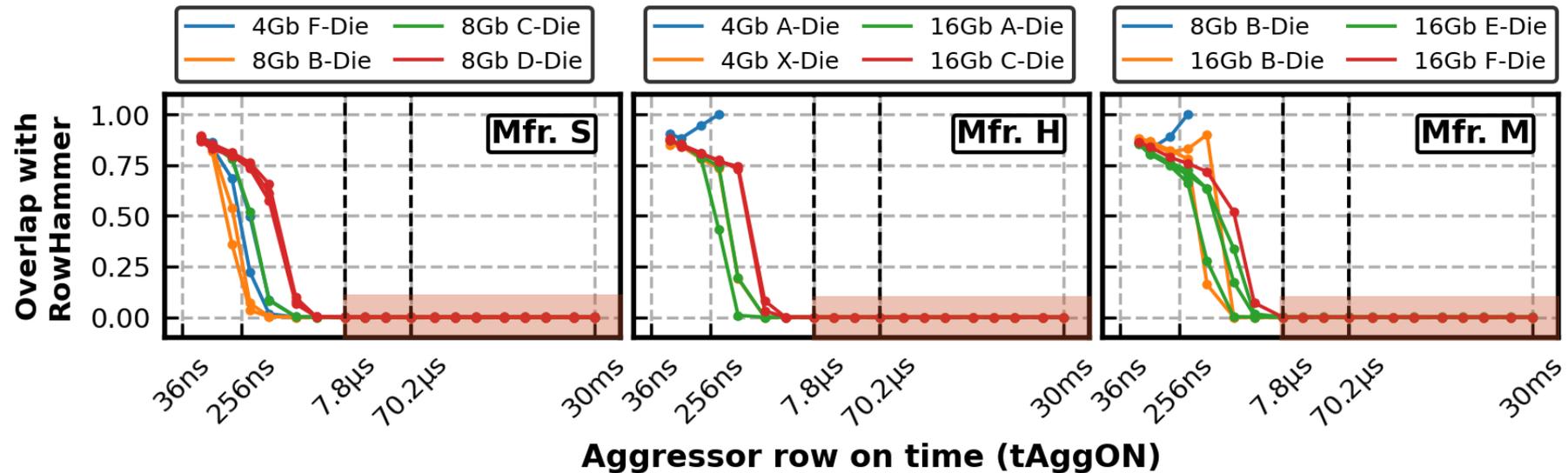


On average, only **0.013%** of DRAM cells vulnerable to RowPress are also vulnerable to RowHammer, when **tAggON ≥ 7.8us**

# Difference Between RowPress and RowHammer (II)

## Cells vulnerable to RowPress vs. RowHammer

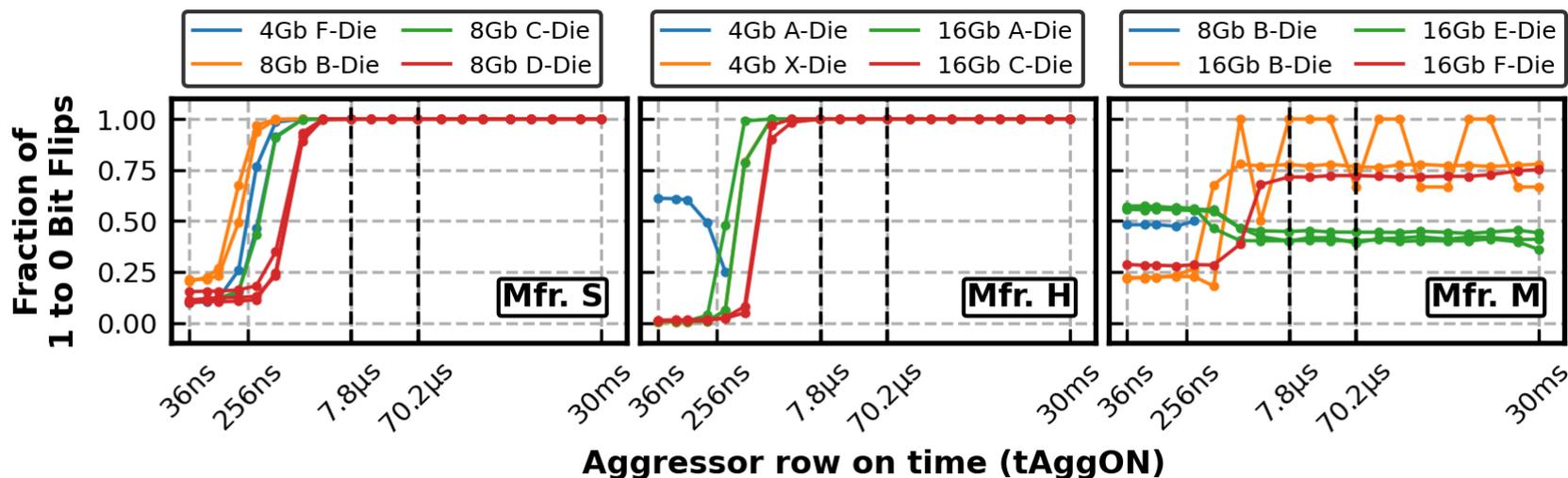
- Cells vulnerable to RowPress (RowHammer) are those that flip @ ACmin
- $$\text{Overlap} = \frac{\text{Number of Cells Vulnerable to Both RowPress and RowHammer}}{\text{Number of Cells Vulnerable to RowPress}}$$



**Most cells vulnerable to RowPress are NOT vulnerable to RowHammer**

# Difference Between RowPress and RowHammer (III)

## Directionality of RowHammer and RowPress bitflips



The majority of **RowHammer** bitflips are **0 to 1**

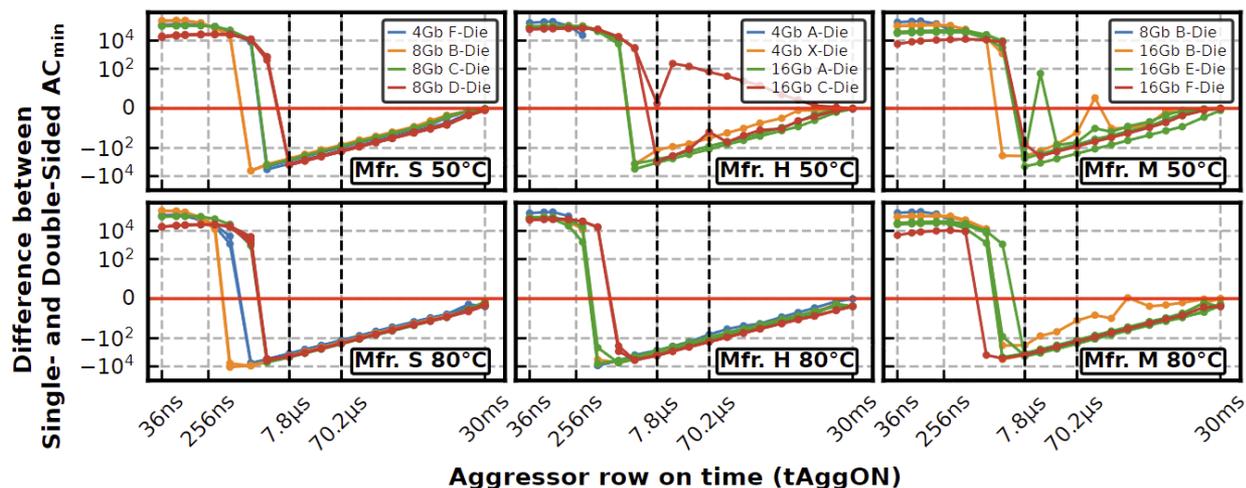
The majority of **RowPress** bitflips are **1 to 0**

**RowPress and RowHammer bitflips have opposite directions**

# Difference Between RowPress and RowHammer (IV)

## Effectiveness of single-sided vs. double-sided RowPress

- Data point below 0 means fewer activations to cause bitflips with single-sided RowPress compared to double-sided RowPress



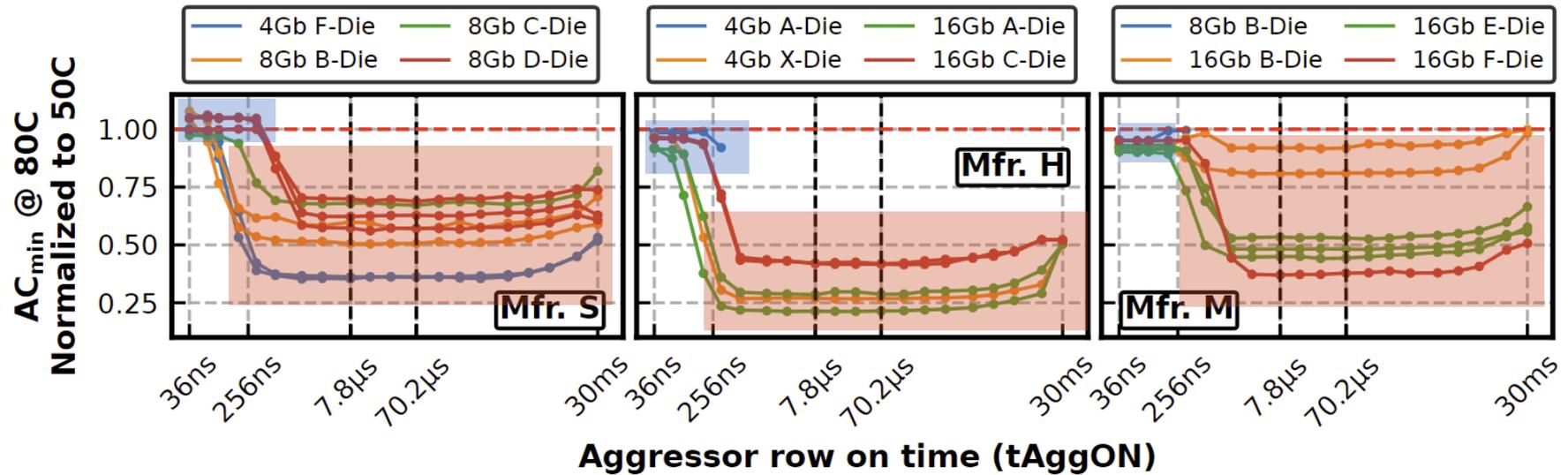
As tAggON increases beyond a certain level, **single-sided RowPress becomes more effective** compared to double-sided

Different from RowHammer where **double-sided is more effective**

# Difference Between RowPress and RowHammer (V)

## Sensitivity to temperature

- Data point below 1 means fewer activations to cause bitflips @ 80°C compared to 50°C



**RowPress gets worse as temperature increases,**  
which is **very different from RowHammer**

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# Real-System Demonstration (I)



Intel Core i5-10400  
(Comet Lake)



Samsung DDR4 Module  
M378A2K43CB1-CTD  
(Date Code: 20-10)  
w/ TRR RowHammer Mitigation

**Key Idea:** A proof-of-concept RowPress program keeps a DRAM row open for a longer period by **keeping on accessing different cache blocks in the row**

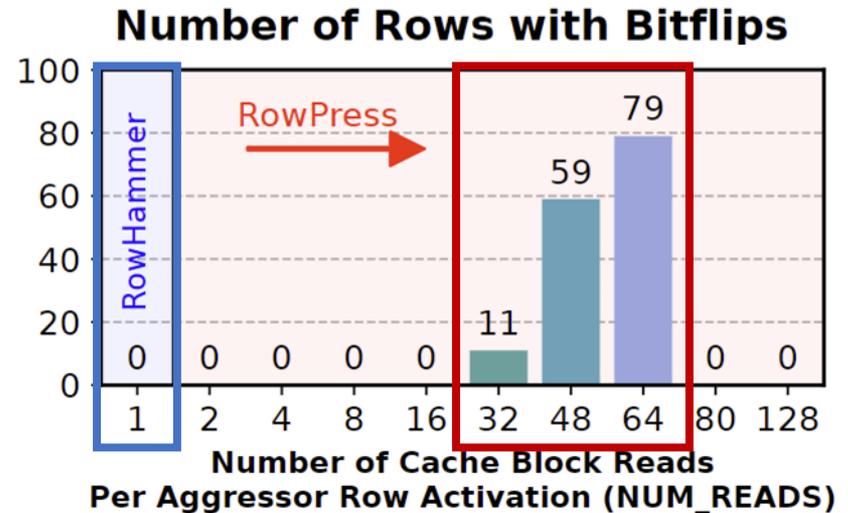
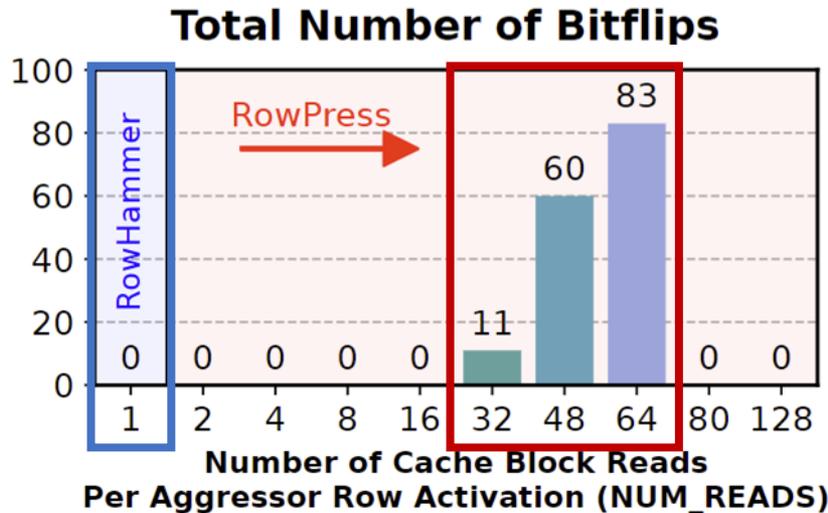
```
// Sync with Refresh and Loop Below
for (k = 0; k < NUM_AGGR_ACTS; k++)
  for (j = 0; j < NUM_READS; j++) *AGGRESSOR1[j];
  for (j = 0; j < NUM_READS; j++) *AGGRESSOR2[j];
  for (j = 0; j < NUM_READS; j++)
    clflushopt (AGGRESSOR1[j]);
    clflushopt (AGGRESSOR2[j]);
  m fence();
activate_dummy_rows();
```

Facilitated by adaptive row policy in  
the memory controller

Number of Cache Blocks Accessed  
Per Aggressor Row ACT  
(NUM\_READS=1 is Rowhammer)

# Real-System Demonstration (II)

On 1500 victim rows



**Leveraging RowPress, our user-level program induces bitflips when RowHammer cannot**

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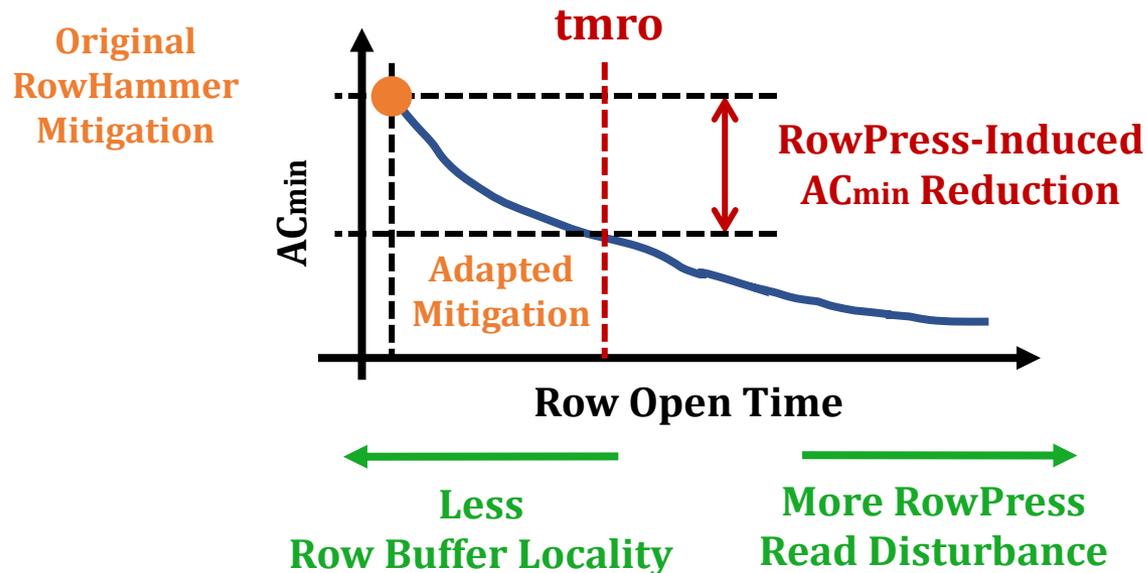
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# Mitigating RowPress (I)

We propose a methodology to adapt existing RowHammer mitigations to **also mitigate RowPress**

## Key Idea:

1. Limit the maximum row open time (**tmro**)
2. Configure the RowHammer mitigation to account for the **RowPress-induced reduction in ACmin**



# Mitigating RowPress (II)

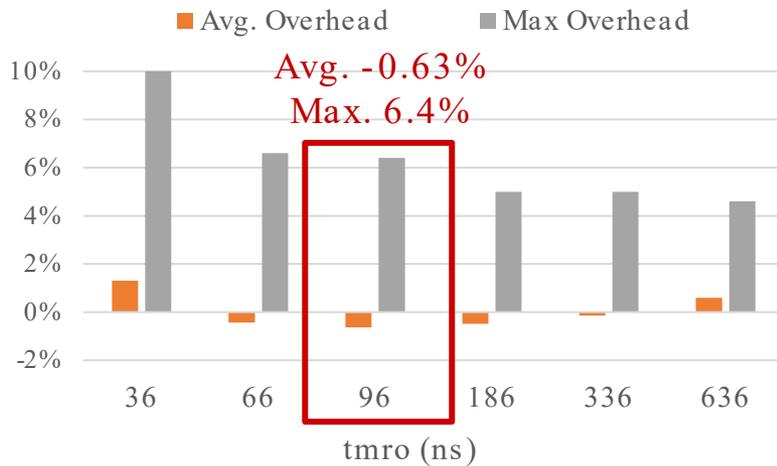
## Evaluation methodology

- **Adapted RowHammer Mitigations: Graphene (Graphene-RP) and PARA (PARA-RP)**
- Cycle-accurate DRAM simulator: Ramulator [Kim+, CAL'15]
  - 4 GHz Out-of-Order Core, dual-rank DDR4 DRAM
  - FR-FCFS scheduling
  - Open-row policy (with limited maximum row open time)
- 58 four-core multiprogrammed workloads from SPEC CPU2017, TPC-H, and YCSB
- **Metric: Additional performance overhead** of Graphene-RP (PARA-RP) over Graphene (PARA)
  - Measured by weighted speedup

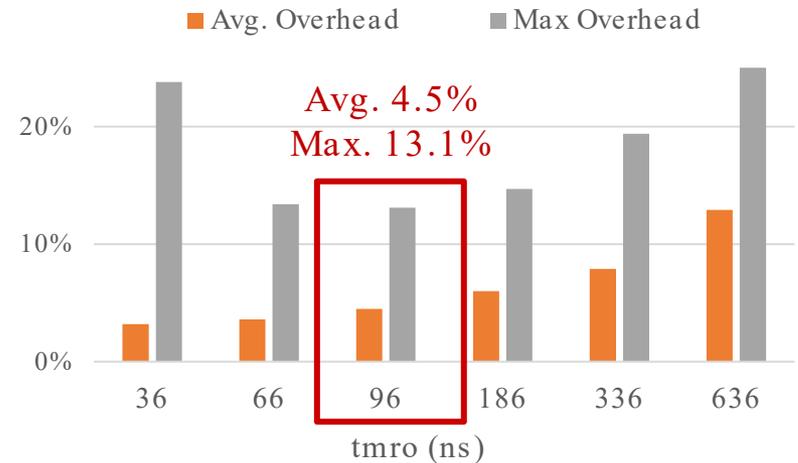
# Mitigating RowPress (III)

## Key evaluation results

Additional Performance Overhead of Graphene-RP



Additional Performance Overhead of PARA-RP



**Our solutions mitigate RowPress at low additional performance overhead**

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# Conclusion

We demonstrate and analyze **RowPress, a widespread read disturbance phenomenon** that causes bitflips in real DRAM chips

We **characterize RowPress** on 164 DDR4 chips from all 3 major DRAM manufacturers

- RowPress greatly **amplifies read disturbance**: minimum activation count **reduces by 1-2 orders of magnitude**
- RowPress has a **different mechanism** from RowHammer & retention failures

We **demonstrate RowPress** using **a user-level program**

- Induces bitflips when RowHammer cannot

We provide **effective solutions** to RowPress

- Low additional performance overhead

# More Results & Source Code

## Many more results & analyses in the paper

- 6 major takeaways
- 19 major empirical observations
- 3 more potential mitigations



## Fully open source and artifact evaluated

- <https://github.com/CMU-SAFARI/RowPress>



# RowPress

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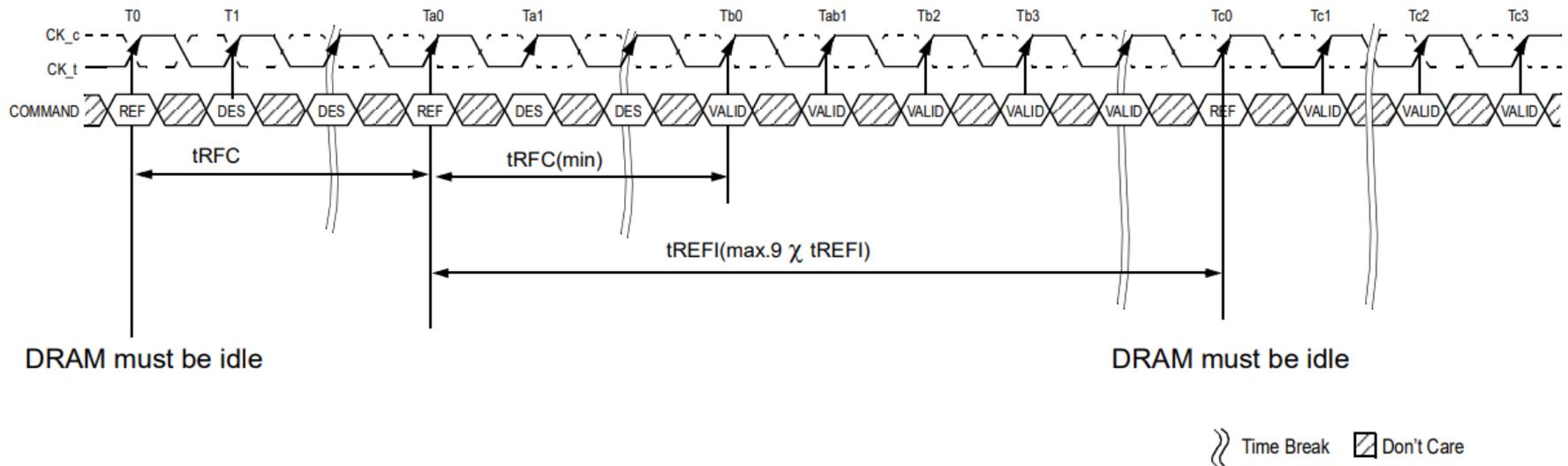
<https://github.com/CMU-SAFARI/RowPress>

**SAFARI**

**ETH** zürich

## Potential tAggON upper bounds

- **tREFI**: Interval between two REF commands
- **9tREFI**:



NOTE 1 Only DES commands allowed after Refresh command registered until tRFC(min) expires.

NOTE 2 Time interval between two Refresh commands may be extended to a maximum of 9 X tREFI.

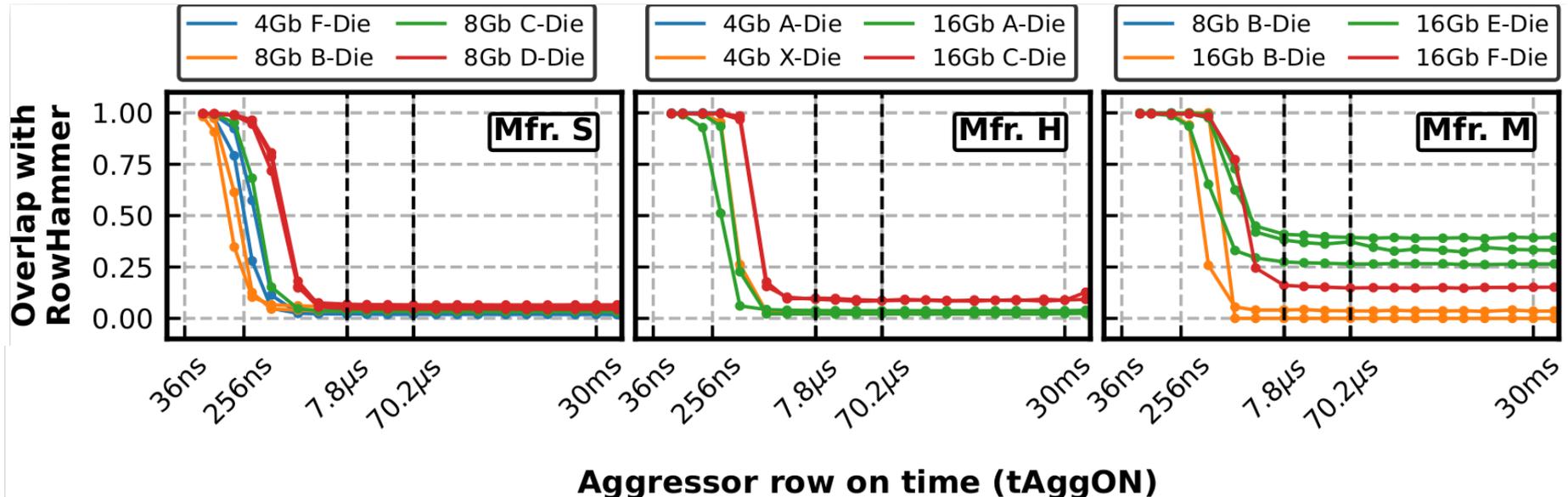
**Figure 157 — Refresh Command Timing (Example of 1x Refresh mode)**

JESD79-4C

# Backup Slide

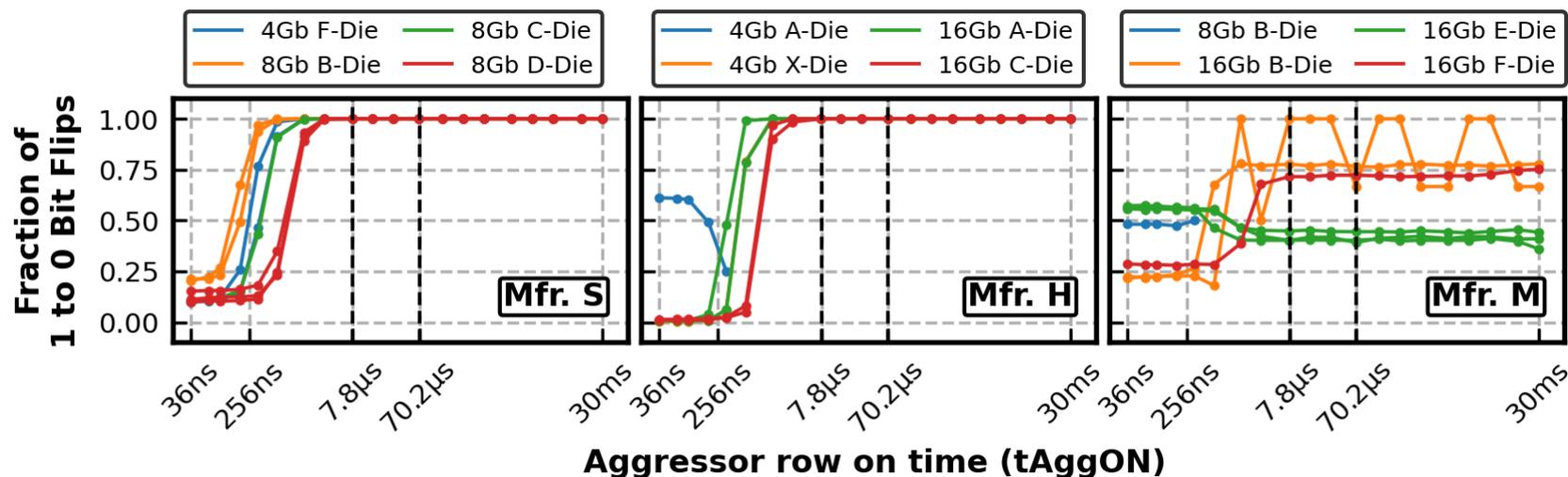
## Cells vulnerable to RowPress vs RowHammer

- Cells vulnerable to RowPress (RowHammer) are those that flip @ ACmax
- $$\text{Overlap} = \frac{\text{Number of Cells Vulnerable to Both RowPress and RowHammer}}{\text{Number of Cells Vulnerable to RowPress}}$$



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## Directionality of RowHammer and RowPress bitflips



The majority of **RowHammer** bitflips are **0 to 1**

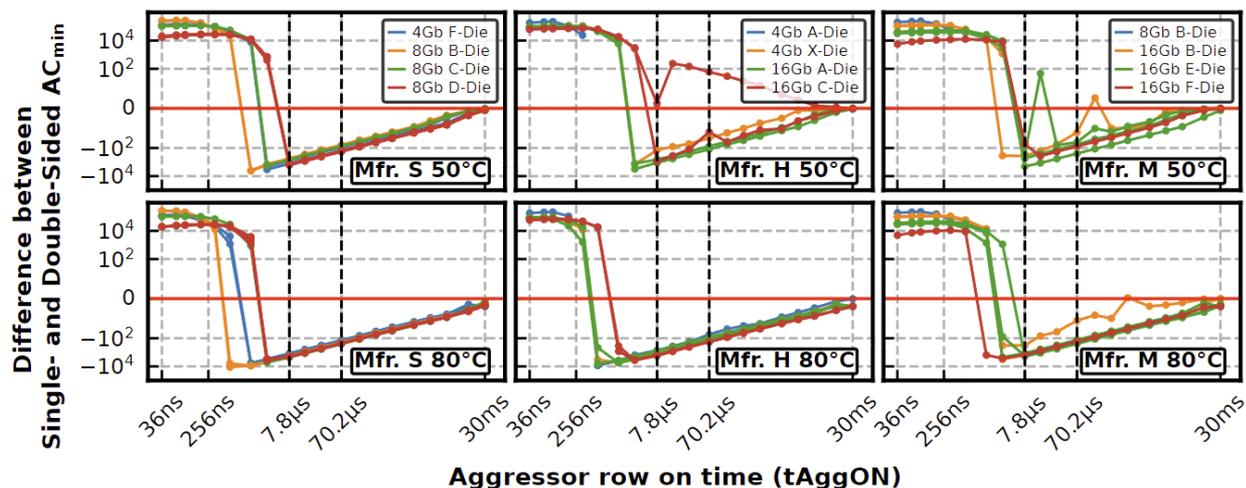
The majority of **RowPress** bitflips are **1 to 0**

**RowPress and RowHammer bitflips have opposite directions**

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## Effectiveness of single-sided vs double-sided RowPress

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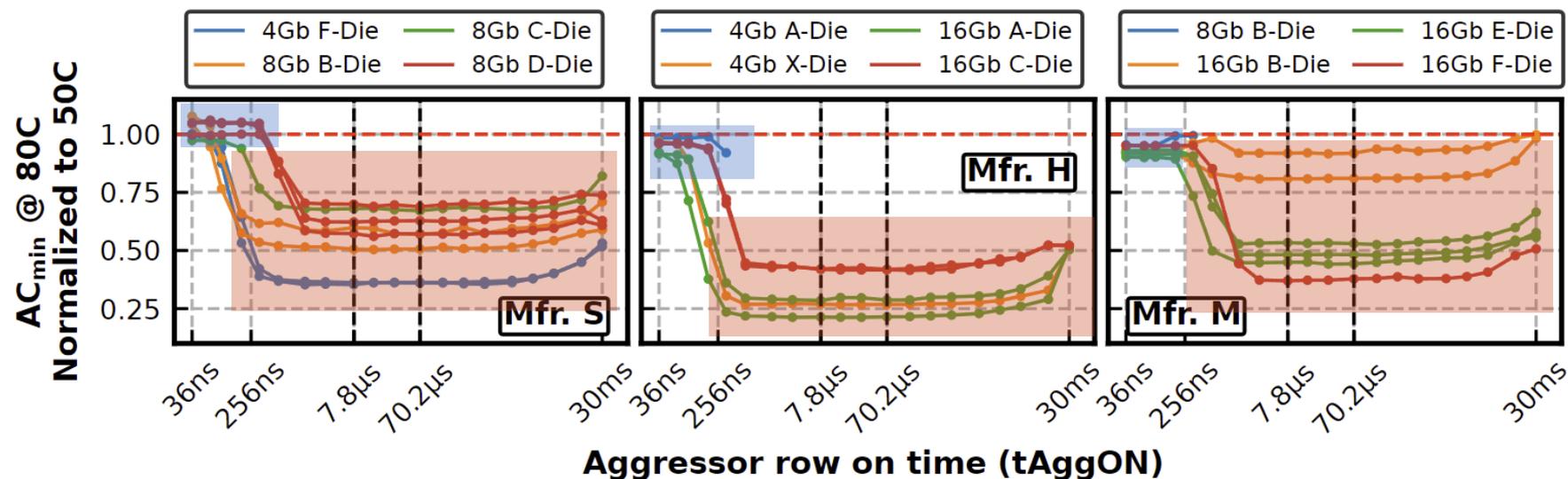
As tAggON increases beyond a certain level, **single-sided RowPress becomes more effective** compared to double-sided

Different from RowHammer where **double-sided is more effective**

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## Sensitivity to temperature

- Data point below 1 means fewer activations to cause bitflips @ 80°C compared to 50°C



**RowPress gets worse as temperature increases,**  
which is **very different from RowHammer**

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**RowPress significantly reduces ACmin as tAggON increases**

**Most Cells Vulnerable to RowPress  
are NOT vulnerable to RowHammer**

**RowPress and RowHammer bitflips have opposite directions**

As tAggON increases beyond a certain level, **single-sided RowPress becomes more effective** compared to double-sided

## Device-Level Explanations

- AWL-induced “1” failure is mainly caused by electron migration during the OFF period of AWL, not affected by increased  $t_{\text{AggON}}$
- AWL-induced “0” failure is mainly caused by the increased victim SN leakage caused by the strong electric field near AWL when AWL is ON
- PWL-induced “0” failure is mainly caused by charge capture by e-traps near PWL, not affected by increased  $t_{\text{AggON}}$  after trap saturation
- PWL-induced “1” failure is mainly caused by the strong electric field near PWL attracting electrons towards the direction of victim SN

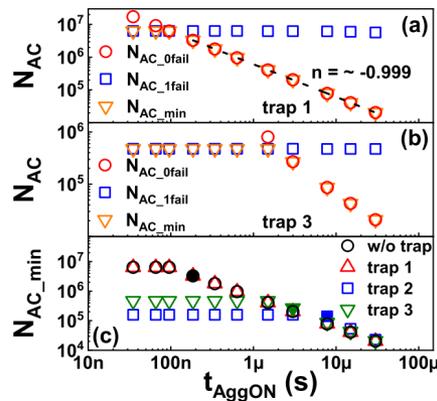


Fig. 3. AWL-induced RH and RP:  $N_{\text{AC}_0\text{fail}}$ ,  $N_{\text{AC}_1\text{fail}}$ , and  $N_{\text{AC}_\text{min}}$  as functions of  $t_{\text{AggON}}$  for (a) trap 1 and (b) trap 3. (c) Dependence of  $N_{\text{AC}_\text{min}}$  on  $t_{\text{AggON}}$  under different trap conditions, highlighted by a solid point at the transition  $t_{\text{AggON}}$ .

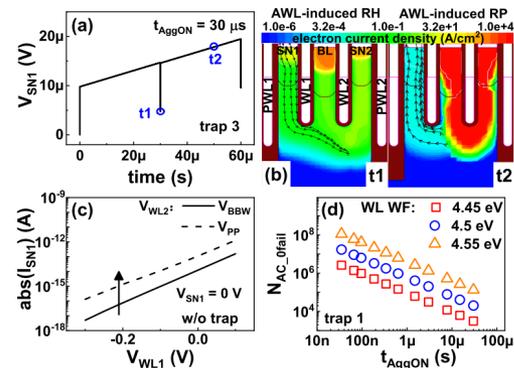


Fig. 4. Analysis of the EM mechanism in AWL-induced RP. (a) Time kinetics of  $V_{\text{SN1}}$  with  $t_{\text{AggON}} = 30 \mu\text{s}$  for “0” failure. (b) ECD contours at different time points in (a) are depicted, along with the direction of the ECD. (c)  $I_{\text{SN1}} - V_{\text{WL1}}$  curves for different  $V_{\text{WL2}}$  conditions. (d) Dependence of  $N_{\text{AC}_0\text{fail}}$  on  $t_{\text{AggON}}$  under different WL WFs.